电子工程专辑 EE Times China

2026 Editorial Calendar

Issue	Cover Story	Trend & Analysis			Design & Technology	
		Industry Trends	Opinions	Interview	Design Corner	Test & Measurement
January Ad Booking Deadline: 21-Nov-2025 Ad Materials Deadline: 28-Nov-2025	New Year Outlook – Beyond AI	•	•	•	- Smart Home/Wearables/Smart Cities - Industrial IoT/Edge Computing - Wireless Communications/Connected Vehicles/Remote Healthcare	Signal Integrity Spectrum/Protocol Analyzers Wireless Testing
February Ad Booking Deadline: 22-Dec-2025 Ad Materials Deadline: 30-Dec-2025	EDA: From Chips to Systems	•	•	•	- PCB Design - Analog Mixed-Signal Design - FPGA/SoC Design	Logic Analyzers Timing Analysis/Signal Generators Simulation Software
March Ad Booking Deadline: 20-Jan-2026 Ad Materials Deadline: 28-Jan-2026	The Battle for Advanced Packaging Technologies	•	•	•	- Chiplet/3D Stacking - High-Density Interconnect - Heterogeneous Integration/Hybrid Bonding	Electrical Performance Testing Thermal Analysis/Failure Analysis Stress and Strain Measurement
April Ad Booking Deadline: 25-Feb-2026 Ad Materials Deadline: 27-Feb-2026	Memory Chips: Who is Defining the "Second Growth Curve" for the AI Era?	•	•	•	- High-Speed Cache Design - Memory Wall Challenges/In-Memory Computing - Neuromorphic Computing	Data Integrity Verification Power Analyzers Logic Analyzers
May Ad Booking Deadline: 20-Mar-2026 Ad Materials Deadline: 30-Mar-2026	A New Core for a New Vision: Unlocking the Smart Glasses Gateway	•	•	•	- AR/VR - Display Technologies/Voice Interaction/Human-Machine Interface - Low-Power/Miniaturized Design	Optical Performance Testing Cybersecurity/Battery Safety Battery Life Testing
June Ad Booking Deadline: 20-Apr-2026 Ad Materials Deadline: 30-Apr-2026	Semiconductor Opportunities in the Emerging Low-Altitude Economy	•	•	•	- IoT Device Security - Key Management/Anti-Tampering Design - Semiconductor Information Security/Encryption Algorithms	Side-Channel Analyzers Logic State Analyzers EMI/EMC
July Ad Booking Deadline: 20-May-2026 Ad Materials Deadline: 29-May-2026	The 800V High-Voltage Platform: Catalyzing Innovation in Automotive Semiconductors	•	•	•	- Batteries/Chargers/Charging Infrastructure - New Energy Vehicles/Electric Vehicles - V2X/SDV/ADAS/Autonomous Driving	Power Integrity Safety Testing Protocol Analyzers/Network Analyzers
August Ad Booking Deadline: 19-Jun-2026 Ad Materials Deadline: 30-Jun-2026	AI Chips: From Cloud to Edge	•	•	•	- Data Center Optimization/Green Computing - Distributed Storage - Cybersecurity	Performance Benchmarking/Power Consumption Measurement Automated Testing Network Latency and Bandwidth Testing
September Ad Booking Deadline: 20-Jul-2026 Ad Materials Deadline: 30-Jul-2026	Latest Developments in the RISC-V Ecosystem	•	•	•	- Processors/Hardware Accelerators - Low-Power Optimization - Embedded Systems	Processor Performance Benchmarking Hardware Emulators Power Analyzers
October Ad Booking Deadline: 20-Aug-2026 Ad Materials Deadline: 28-Aug-2026	The Chip Revolution Behind the Humanoid Robot Boom	•	•	•	- Vision Sensors/LiDAR - IMU/Tactile Sensors/Biosensors - Positioning and Navigation	Resolution Analyzers Dynamic Range Testing Sensor Fusion Testing
November Ad Booking Deadline: 21-Sep-2026 Ad Materials Deadline: 25-Sep-2026	Wide Bandgap Semiconductors Go Mainstream	•	•	•	- High-Efficiency Motor Drives - New Energy/Smart Grids - Inverter Technologies	Power Integrity Testing Bench Power Supplies/Thermal Analysis High-Precision Oscilloscopes
December Ad Booking Deadline: 20-Oct-2026 Ad Materials Deadline: 30-Oct-2026	The Evolution of Domestic GPUs	•	•	•	- Multi-Core Processors/High-Performance Computing - Multimedia Processing - AR/VR/AI Acceleration	Power Analyzers Thermal Imaging Cameras Performance Benchmarking/Compatibility Testing

** Simplified Chinese only*

Editorial inquiries
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Note: The publisher retains the right to reschedule any topic in the calendar.

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